

Study on Thermal Conductivity and Mechanical Properties of Cyclotriphosphazene Resin-Forced Epoxy Resin Composites

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Supplementary information



Figure S1. A samples preparation procedure [26].

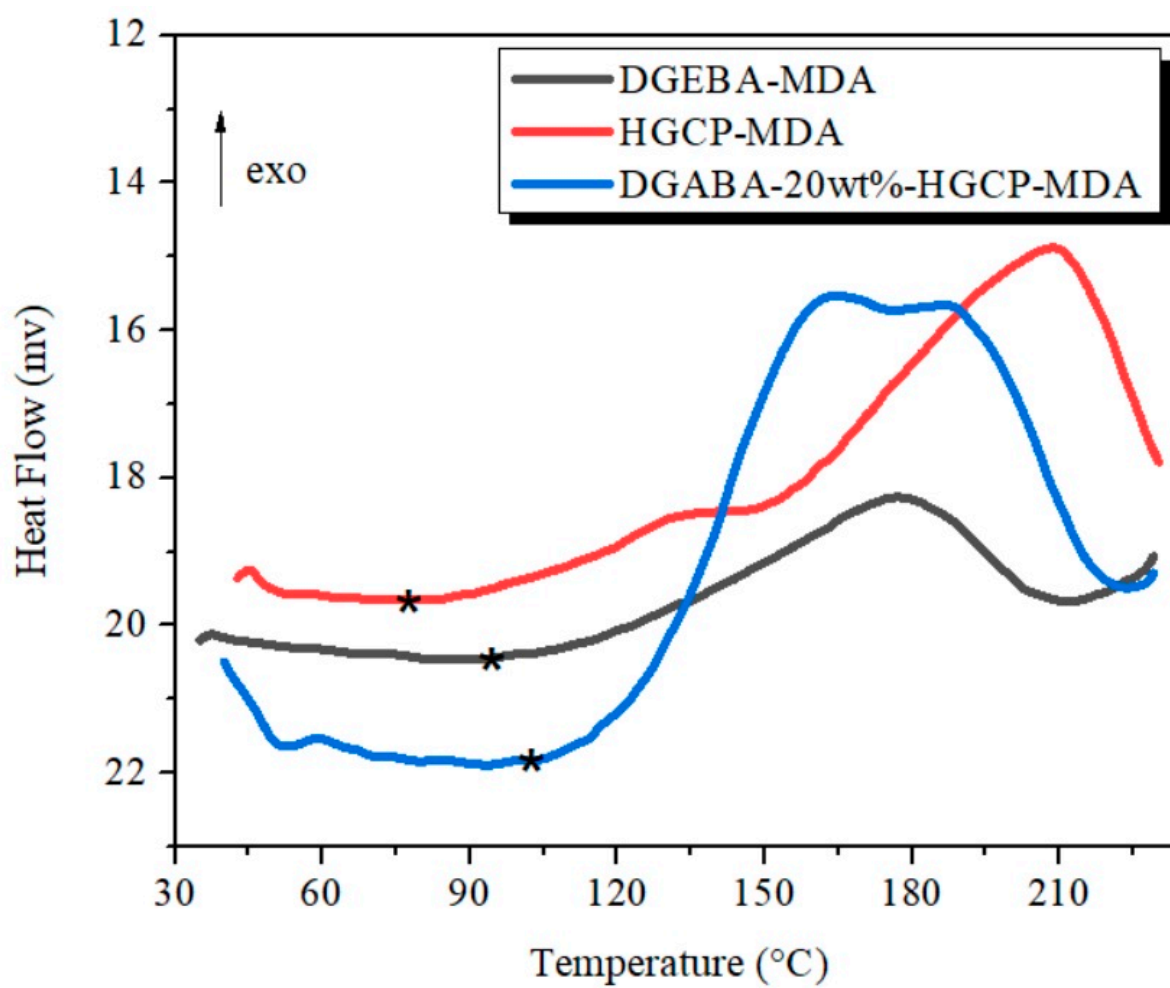


Figure S2. DSC thermograms of materials DGEBA@MDA, HGCP@MDA and DGEBA@HGCP20%@MDA [24].

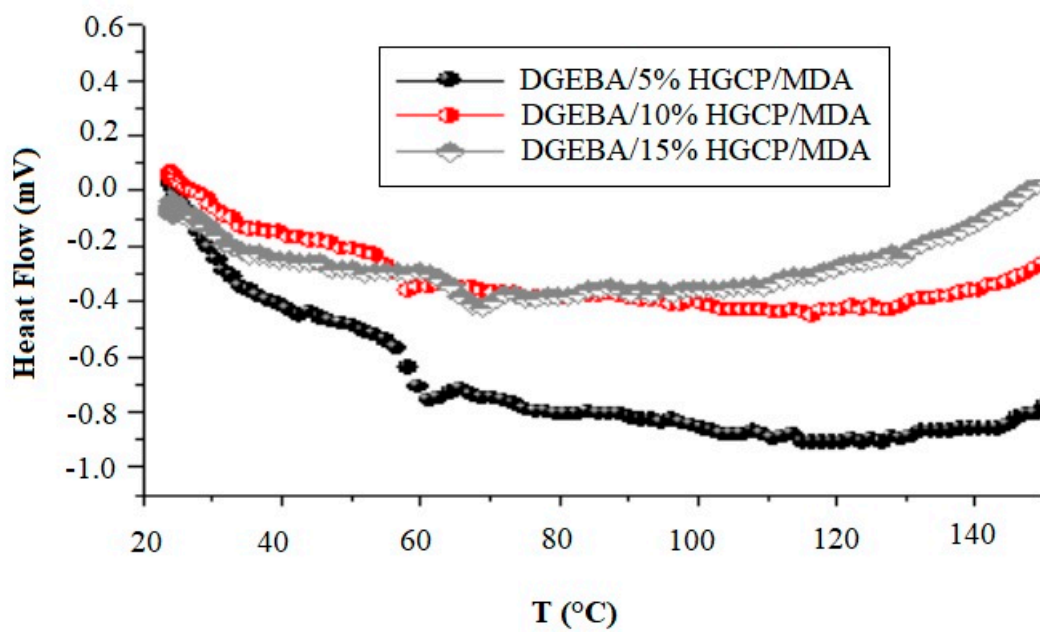


Figure S3. DSC thermograms of materials DGEBA@HGCP5%@MDA, DGEBA@HGCP10%@MDA and DGEBA@HGCP15%@MDA [37].